

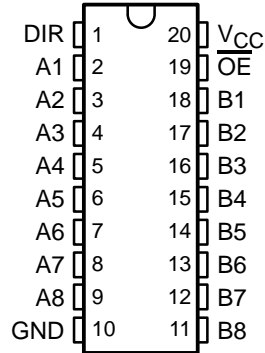
# SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

- 3-State Outputs Drive Bus Lines Directly
- PNP Inputs Reduce dc Loading on Bus Lines
- Hysteresis at Bus Inputs Improves Noise Margins
- Typical Propagation Delay Times Port to Port, 8 ns

TYPE	I <sub>OL</sub> (SINK CURRENT)	I <sub>OH</sub> (SOURCE CURRENT)
SN54LS245	12 mA	–12 mA
SN74LS245	24 mA	–15 mA

SN54LS245 . . . J OR W PACKAGE  
SN74LS245 . . . DB, DW, N, OR NS PACKAGE  
(TOP VIEW)

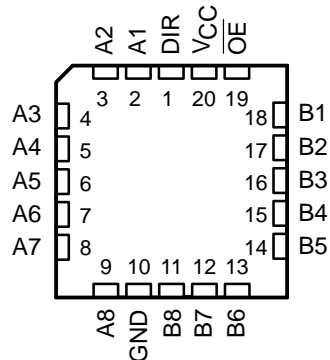


## description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{\text{OE}}$ ) input can disable the device so that the buses are effectively isolated.

SN54LS245 . . . FK PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74LS245N	SN74LS245N
	SOIC – DW	Tube	SN74LS245DW	LS245
		Tape and reel	SN74LS245DWR	
	SOP – NS	Tape and reel	SN74LS245NSR	74LS245
–55°C to 125°C	SSOP – DB	Tape and reel	SN74LS245DBR	LS245
	CDIP – J	Tube	SN54LS245J	SN54LS245J
		Tube	SNJ54LS245J	SNJ54LS245J
	CFP – W	Tube	SNJ54LS245W	SNJ54LS245W
	LCCC – FK	Tube	SN54LS245FK	SN54LS245FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

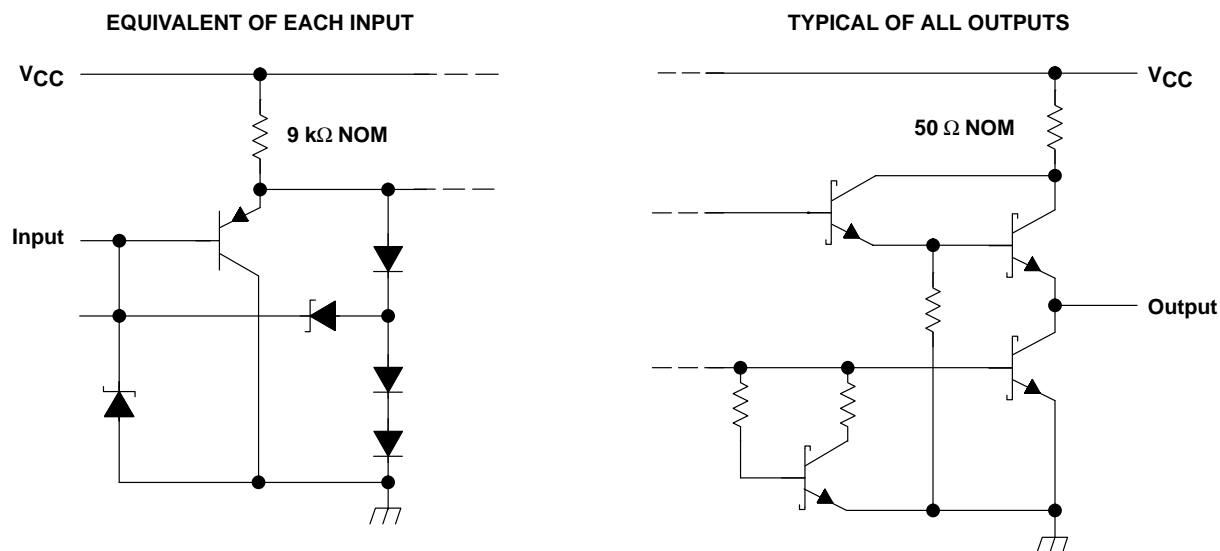
## SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

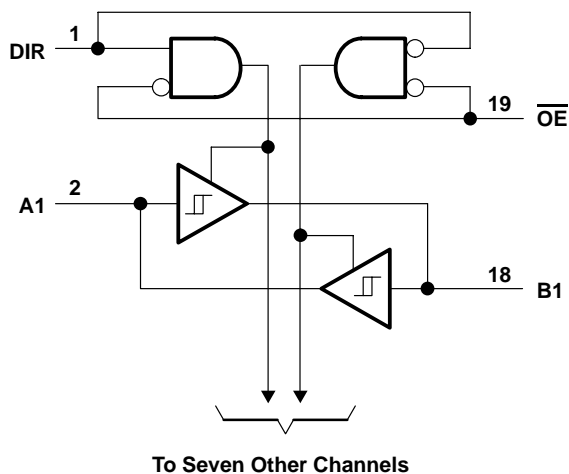
## FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

## schematics of inputs and outputs



**logic diagram (positive logic)**



# SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$ (see Note 1)	7 V
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions

		SN54LS245			SN74LS245			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$I_{OH}$	High-level output current			–12			–15	mA
$I_{OL}$	Low-level output current			12			24	mA
$T_A$	Operating free-air temperature	–55		125	0		70	°C



# SN54LS245, SN74LS245

## OCTAL BUS TRANSCEIVERS

### WITH 3-STATE OUTPUTS

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER			TEST CONDITIONS†		SN54LS245			SN74LS245			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IH</sub>	High-level input voltage				2			2			V
V <sub>IL</sub>	Low-level input voltage				0.7			0.8			V
V <sub>IK</sub>	Input clamp voltage		V <sub>CC</sub> = MIN, I <sub>I</sub> = −18 mA		−1.5			−1.5			V
Hysteresis (V <sub>T+</sub> − V <sub>T−</sub> )		A or B	V <sub>CC</sub> = MIN		0.2	0.4		0.2	0.4		V
V <sub>OH</sub>	High-level output voltage		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL(max)</sub>	I <sub>OH</sub> = −3 mA	2.4	3.4		2.4	3.4		V
				I <sub>OH</sub> = MAX	2		2				
V <sub>OL</sub>	Low-level output voltage		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL(max)</sub>	I <sub>OL</sub> = 12 mA	0.4			0.4			V
				I <sub>OL</sub> = 24 mA				0.5			
I <sub>OZH</sub>	Off-state output current, high-level voltage applied		V <sub>CC</sub> = MAX, $\overline{\text{OE}}$ at 2 V	V <sub>O</sub> = 2.7 V	20			20			μA
I <sub>OZL</sub>	Off-state output current, low-level voltage applied		V <sub>CC</sub> = MAX, $\overline{\text{OE}}$ at 2 V	V <sub>O</sub> = 0.4 V	−200			−200			μA
I <sub>I</sub>	Input current at maximum input voltage	A or B	V <sub>CC</sub> = MAX	V <sub>I</sub> = 5.5 V	0.1			0.1			mA
		DIR or $\overline{\text{OE}}$		V <sub>I</sub> = 7 V	0.1			0.1			
I <sub>IH</sub>	High-level input current		V <sub>CC</sub> = MAX, V <sub>IH</sub> = 2.7 V	20			20			μA	
I <sub>IL</sub>	Low-level input current		V <sub>CC</sub> = MAX, V <sub>IL</sub> = 0.4 V	−0.2			−0.2			mA	
I <sub>OS</sub>	Short-circuit output current§		V <sub>CC</sub> = MAX	−40	−225		40	−225		mA	
I <sub>CC</sub>	Supply current	Total, outputs high	V <sub>CC</sub> = MAX      Outputs open	48    70		48    70				mA	
		Total, outputs low		62    90		62    90					
		Outputs at high Z		64    95		64    95					

† For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

§ Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

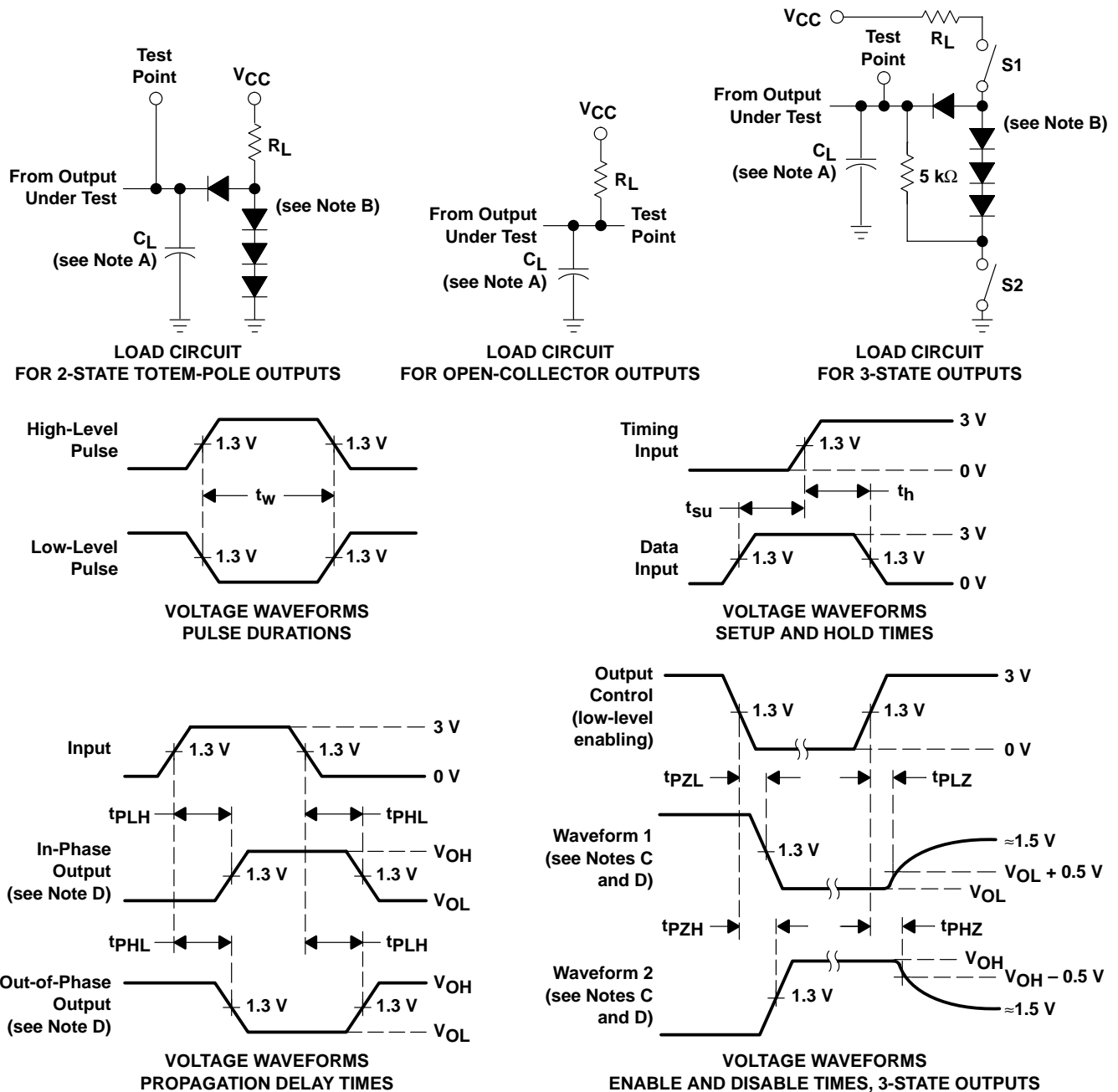
### switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ (see Figure 1)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{PLH}$	Propagation delay time, low- to high-level output		8	12	ns
$t_{PHL}$	Propagation delay time, high- to low-level output		8	12	
$t_{PZL}$	Output enable time to low level		27	40	ns
$t_{PZH}$	Output enable time to high level		25	40	
$t_{PLZ}$	Output disable time from low level		15	25	ns
$t_{PHZ}$	Output disable time from high level		15	28	



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PARAMETER MEASUREMENT INFORMATION  
SERIES 54LS/74LS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. All diodes are 1N3064 or equivalent.  
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
D. S1 and S2 are closed for  $t_{PLH}$ ,  $t_{PHL}$ ,  $t_{PHZ}$ , and  $t_{PLZ}$ ; S1 is open and S2 is closed for  $t_{PZH}$ ; S1 is closed and S2 is open for  $t_{PZL}$ .  
E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.  
F. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O \approx 50 \Omega$ ,  $t_r \leq 1.5$  ns,  $t_f \leq 2.6$  ns.  
G. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8002101VSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8002101VS A SNV54LS245W	<a href="#">Samples</a>
80021012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	80021012A SNJ54LS 245FK	<a href="#">Samples</a>
8002101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8002101SA SNJ54LS245W	<a href="#">Samples</a>
JM38510/32803B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32803B2A	<a href="#">Samples</a>
JM38510/32803BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32803BRA	<a href="#">Samples</a>
JM38510/32803BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32803BSA	<a href="#">Samples</a>
M38510/32803B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32803B2A	<a href="#">Samples</a>
M38510/32803BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32803BRA	<a href="#">Samples</a>
M38510/32803BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32803BSA	<a href="#">Samples</a>
SN54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS245J	<a href="#">Samples</a>
SN74LS245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS245	<a href="#">Samples</a>
SN74LS245J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	0 to 70		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS245N	<a href="#">Samples</a>
SN74LS245N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74LS245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS245N	<a href="#">Samples</a>
SN74LS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS245	<a href="#">Samples</a>
SN74LS245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS245	<a href="#">Samples</a>
SNJ54LS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	80021012A SNJ54LS 245FK	<a href="#">Samples</a>
SNJ54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS245J	<a href="#">Samples</a>
SNJ54LS245W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8002101SA SNJ54LS245W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54LS245, SN54LS245-SP, SN74LS245 :**

- Catalog: [SN74LS245](#), [SN54LS245](#)
- Military: [SN54LS245](#)
- Space: [SN54LS245-SP](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application



**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LS245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS245NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS245DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74LS245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS245NSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

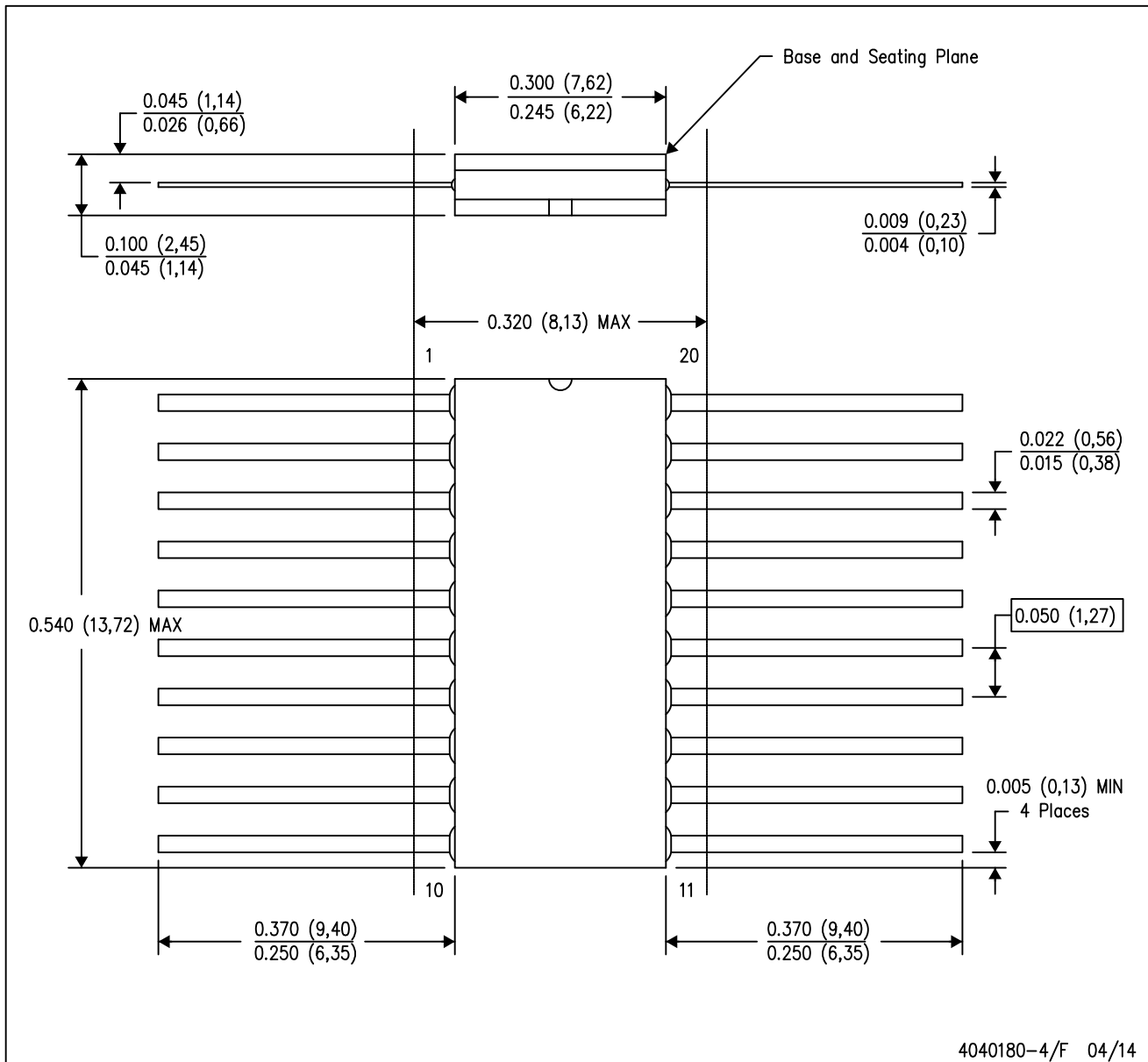


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

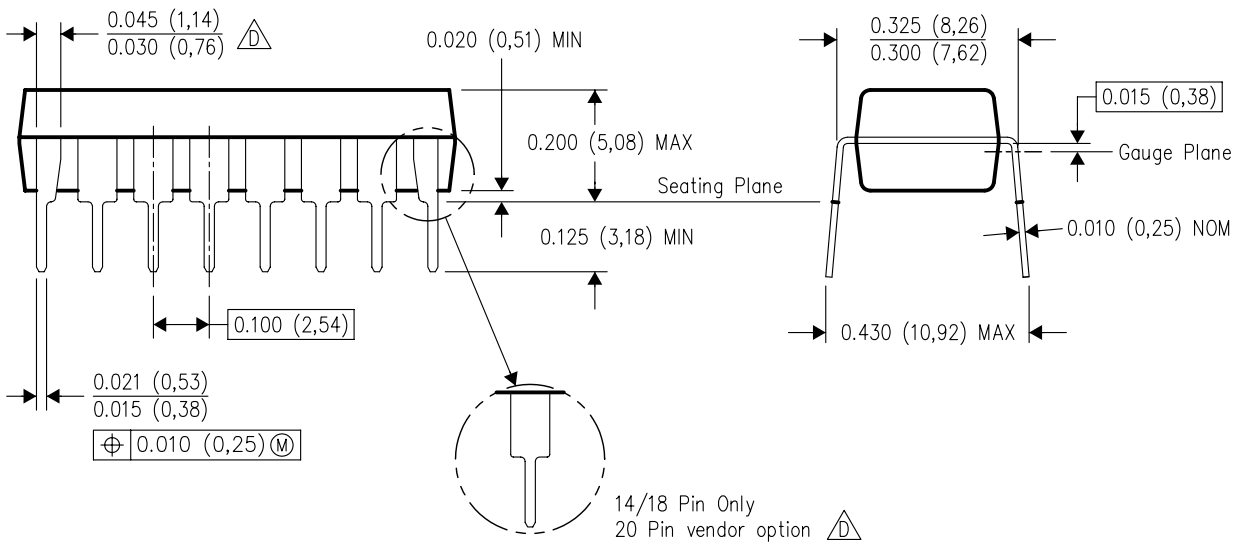
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

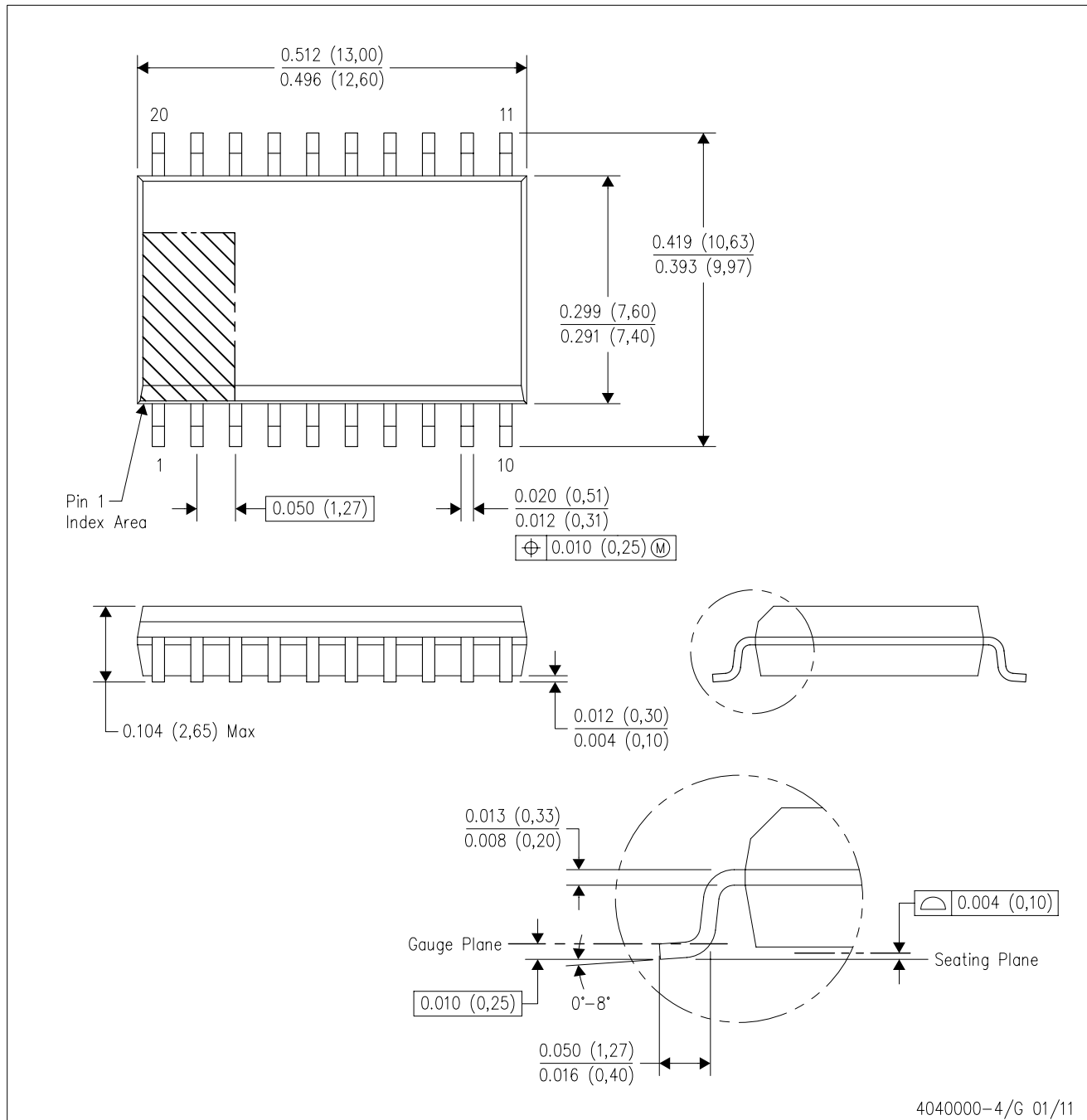


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

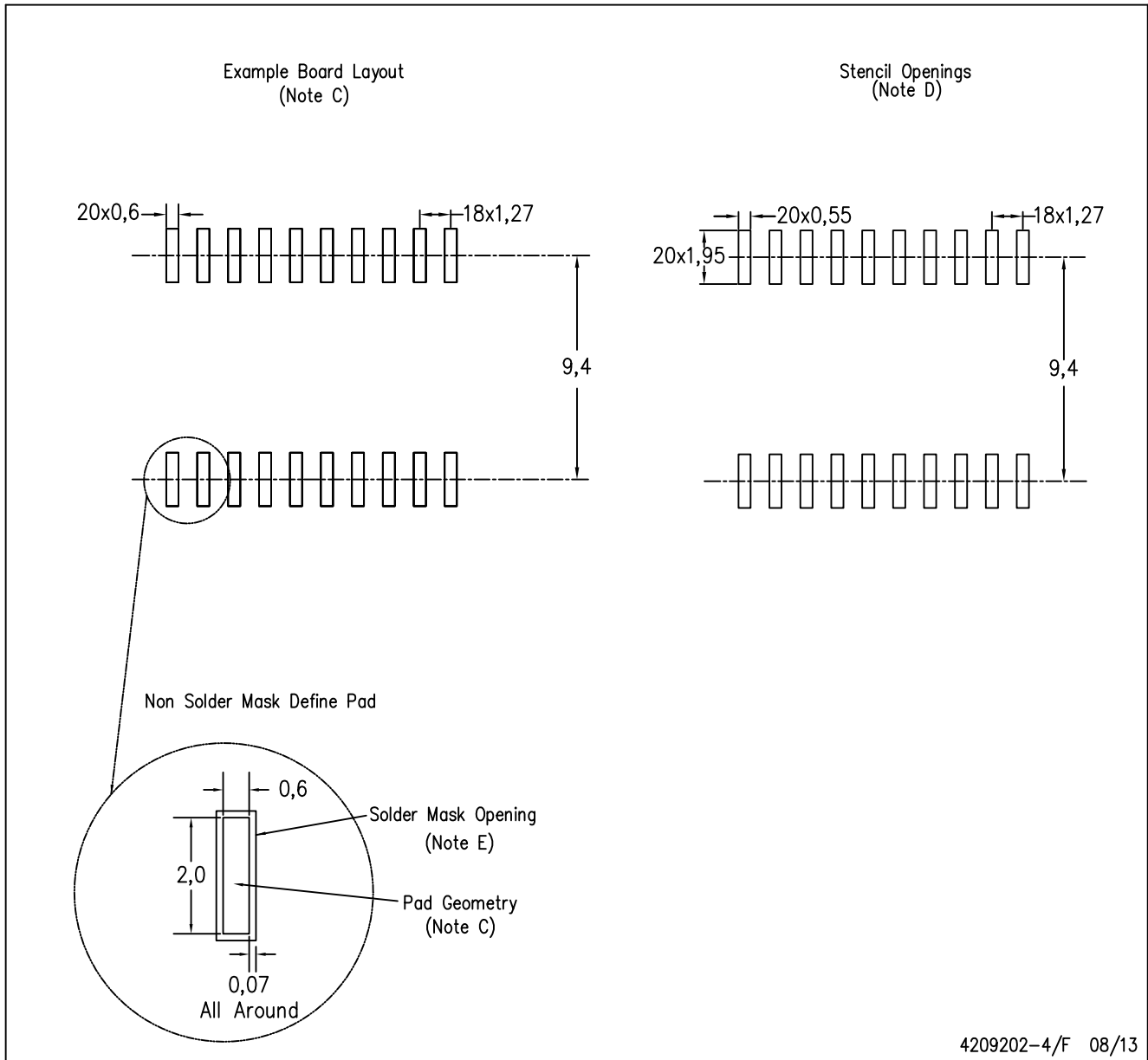
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

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